

Rev.A	Minor note change	3.20.18	RN
		5.20.10	1 1 1

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-Anode: 10nm + - 3 of NiCr - inside bottom surface. See note 2

-Border : 200nm of NiCr followed by 200nm of Cu. See note 3.

-Sidewall Seal Surfaces: 200nm of NiCr followed by 200nm of Cu without a vacuum break. See note 4.

## Notes-

- 1. Tile base as specified in Univ.of Chicago print CeramTB111617revE.
- 2. Anode consists of 10nm of NiCr. Film can come up to sidewall. Sidewall to be masked so that no metallization is on it.
- 3. Border consists of 200nm of NiCr followed by 200nm of Cu without a vacuum break between depositions. Border is applied on top of the anode layer and should make electrical contact.
- 4. The sidewall seal surface consists of 200nm of NiCr followed by 200nm of Cu without a vacuum break between depositions. Metallization to pass Scotch Tape adhesion test.
- 5. Top surface of Cu frame to be flat to 0.0005" and parallel to top surface of base within + .005".
- 6. No overspray on sidewall inner or outside.

DRAWN rnorthrop CHECKED	3/9/2018	University of Chicago	
QA MFG		Ceramic Tile Base Assembly	
APPROVED			
		C CoatedTBAssm03	30918 <b>A</b>
		SCALE .85 SHEE	T 1 OF 1